

# (19) United States

# (12) Patent Application Publication (10) Pub. No.: US 2022/0353996 A1 ITO et al.

(43) **Pub. Date:** 

Nov. 3, 2022

## (54) ELECTRONIC DEVICE

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(21) Appl. No.: 17/867,255

(22) Filed: Jul. 18, 2022

## Related U.S. Application Data

Continuation of application No. PCT/JP2021/ 014762, filed on Apr. 7, 2021.

#### (30)Foreign Application Priority Data

Apr. 10, 2020 (JP) ...... 2020-071347

### **Publication Classification**

(51) Int. Cl. H05K 1/18

(2006.01)

### (52) U.S. Cl.

CPC ... H05K 1/181 (2013.01); H05K 2201/09545 (2013.01)

#### (57)**ABSTRACT**

An electronic device includes a component mounting portion, an electronic component disposed on the component mounting portion, a solder between the component mounting portion and the electronic component, a mounting base member, and a supporting beam connecting the component mounting portion and the mounting base member. The supporting beam has a plurality of bent portions. The supporting beam includes a frame, an outer supporting portion connecting the frame and the mounting base member, and an inner supporting portion connecting the frame and the component mounting portion. The inner supporting portion is shifted from the outer supporting portion along the frame. One of the plurality of bent portions is a connecting portion between the frame and the outer supporting portion. Another of the plurality of bent portions is a connecting portion between the frame and the inner supporting portion.

